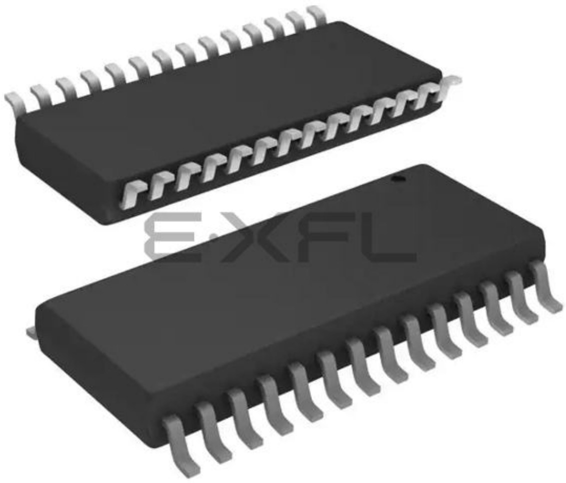

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Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	7KB (4K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	A/D 5x8b
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc73at-04-so

Table of Contents

For register and module descriptions in this data sheet, device legends show which devices apply to those sections. As an example, the legend below would mean that the following section applies only to the PIC16C72, PIC16C73A and PIC16C74A devices.

Applicable Devices						
72	73	73A	74	74A	76	77

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NOTES:

FIGURE 4-4: PIC16C72 REGISTER FILE MAP

File Address	Bank 0	Bank 1	File Address
00h	INDF(1)	INDF(1)	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h	PORTC	TRISC	87h
08h			88h
09h			89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh			8Dh
0Eh	TMR1L	PCON	8Eh
0Fh	TMR1H		8Fh
10h	T1CON		90h
11h	TMR2		91h
12h	T2CON	PR2	92h
13h	SSPBUF	SSPADD	93h
14h	SSPCON	SSPSTAT	94h
15h	CCPR1L		95h
16h	CCPR1H		96h
17h	CCP1CON		97h
18h			98h
19h			99h
1Ah			9Ah
1Bh			9Bh
1Ch			9Ch
1Dh			9Dh
1Eh	ADRES		9Eh
1Fh	ADCON0	ADCON1	9Fh
20h	General Purpose Register	General Purpose Register	A0h
			BFh
			C0h
7Fh			FFh

Shaded cells: Unimplemented data memory locations, read as '0'.

Note 1: Not a physical register.

FIGURE 4-5: PIC16C73/73A/74/74A REGISTER FILE MAP

File Address	Bank 0	Bank 1	File Address
00h	INDF(1)	INDF(1)	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h	PORTC	TRISC	87h
08h	PORTD(2)	TRISD(2)	88h
09h	PORTE(2)	TRISE(2)	89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh	PIR2	PIE2	8Dh
0Eh	TMR1L	PCON	8Eh
0Fh	TMR1H		8Fh
10h	T1CON		90h
11h	TMR2		91h
12h	T2CON	PR2	92h
13h	SSPBUF	SSPADD	93h
14h	SSPCON	SSPSTAT	94h
15h	CCPR1L		95h
16h	CCPR1H		96h
17h	CCP1CON		97h
18h	RCSTA	TXSTA	98h
19h	TXREG	SPBRG	99h
1Ah	RCREG		9Ah
1Bh	CCPR2L		9Bh
1Ch	CCPR2H		9Ch
1Dh	CCP2CON		9Dh
1Eh	ADRES		9Eh
1Fh	ADCON0	ADCON1	9Fh
20h	General Purpose Register	General Purpose Register	A0h
7Fh			FFh

Shaded cells: Unimplemented data memory locations, read as '0'.

Note 1: Not a physical register.

2: These registers are not physically implemented on the PIC16C73/73A, read as '0'.

FIGURE 4-13: PIR1 REGISTER PIC16C73/73A/74/74A/76/77 (ADDRESS 0Ch)

R/W-0	R/W-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
- n = Value at POR reset

bit 7: **PSPIF(1):** Parallel Slave Port Read/Write Interrupt Flag bit
1 = A read or a write operation has taken place (must be cleared in software)
0 = No read or write has occurred

bit 6: **ADIF**: A/D Converter Interrupt Flag bit
1 = An A/D conversion completed (must be cleared in software)
0 = The A/D conversion is not complete

bit 5: **RCIF**: USART Receive Interrupt Flag bit
1 = The USART receive buffer is full (cleared by reading RCREG)
0 = The USART receive buffer is empty

bit 4: **TXIF**: USART Transmit Interrupt Flag bit
1 = The USART transmit buffer is empty (cleared by writing to TXREG)
0 = The USART transmit buffer is full

bit 3: **SSPIF**: Synchronous Serial Port Interrupt Flag bit
1 = The transmission/reception is complete (must be cleared in software)
0 = Waiting to transmit/receive

bit 2: **CCP1IF**: CCP1 Interrupt Flag bit
Capture Mode
1 = A TMR1 register capture occurred (must be cleared in software)
0 = No TMR1 register capture occurred
Compare Mode
1 = A TMR1 register compare match occurred (must be cleared in software)
0 = No TMR1 register compare match occurred
PWM Mode
Unused in this mode

bit 1: **TMR2IF**: TMR2 to PR2 Match Interrupt Flag bit
1 = TMR2 to PR2 match occurred (must be cleared in software)
0 = No TMR2 to PR2 match occurred

bit 0: **TMR1IF**: TMR1 Overflow Interrupt Flag bit
1 = TMR1 register overflowed (must be cleared in software)
0 = TMR1 register did not overflow

Note 1: PIC16C73/73A/76 devices do not have a Parallel Slave Port implemented, this bit location is reserved on these devices, always maintain this bit clear.

> Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

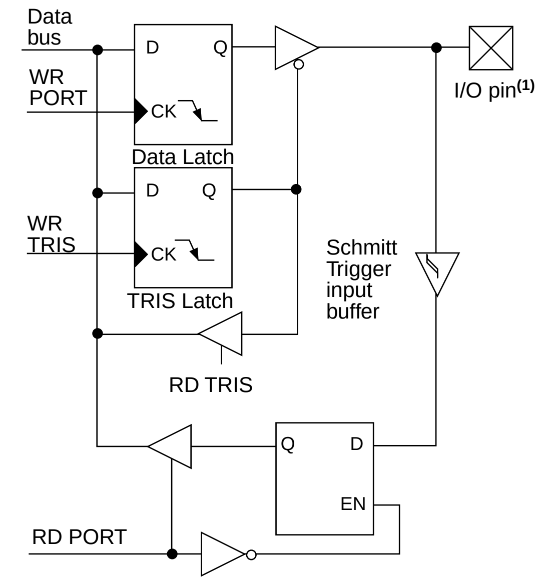
5.4 PORTD and TRISD Registers

Applicable Devices						
72	73	73A	74	74A	76	77

PORTD is an 8-bit port with Schmitt Trigger input buffers. Each pin is individually configurable as an input or output.

PORTD can be configured as an 8-bit wide microprocessor port (parallel slave port) by setting control bit PSPMODE (TRISE<4>). In this mode, the input buffers are TTL.

FIGURE 5-7: PORTD BLOCK DIAGRAM (IN I/O PORT MODE)



Note 1: I/O pins have protection diodes to VDD and VSS.

TABLE 5-7: PORTD FUNCTIONS

Name	Bit#	Buffer Type	Function
RD0/PSP0	bit0	ST/TTL(1)	Input/output port pin or parallel slave port bit0
RD1/PSP1	bit1	ST/TTL(1)	Input/output port pin or parallel slave port bit1
RD2/PSP2	bit2	ST/TTL(1)	Input/output port pin or parallel slave port bit2
RD3/PSP3	bit3	ST/TTL(1)	Input/output port pin or parallel slave port bit3
RD4/PSP4	bit4	ST/TTL(1)	Input/output port pin or parallel slave port bit4
RD5/PSP5	bit5	ST/TTL(1)	Input/output port pin or parallel slave port bit5
RD6/PSP6	bit6	ST/TTL(1)	Input/output port pin or parallel slave port bit6
RD7/PSP7	bit7	ST/TTL(1)	Input/output port pin or parallel slave port bit7

Legend: ST = Schmitt Trigger input TTL = TTL input
Note 1: Input buffers are Schmitt Triggers when in I/O mode and TTL buffer when in Parallel Slave Port Mode.

TABLE 5-8: SUMMARY OF REGISTERS ASSOCIATED WITH PORTD

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
08h	PORTD	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	xxxx xxxx	uuuu uuuu
88h	TRISD	PORTD Data Direction Register								1111 1111	1111 1111
89h	TRISE	IBF	OBF	IBOV	PSPMODE	—	PORTE Data Direction Bits			0000 -111	0000 -111

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used by PORTD.

NOTES:

8.1 Timer1 Operation in Timer Mode

Applicable Devices						
72	73	73A	74	74A	76	77

Timer mode is selected by clearing the TMR1CS (T1CON<1>) bit. In this mode, the input clock to the timer is FOSC/4. The synchronize control bit $\overline{\text{T1SYNC}}$ (T1CON<2>) has no effect since the internal clock is always in sync.

8.2 Timer1 Operation in Synchronized Counter Mode

Applicable Devices						
72	73	73A	74	74A	76	77

Counter mode is selected by setting bit TMR1CS. In this mode the timer increments on every rising edge of clock input on pin RC1/T1OSI/CCP2 when bit T1OSCEN is set or pin RC0/T1OSO/T1CKI when bit T1OSCEN is cleared.

If $\overline{\text{T1SYNC}}$ is cleared, then the external clock input is synchronized with internal phase clocks. The synchronization is done after the prescaler stage. The prescaler stage is an asynchronous ripple-counter.

In this configuration, during SLEEP mode, Timer1 will not increment even if the external clock is present, since the synchronization circuit is shut off. The prescaler however will continue to increment.

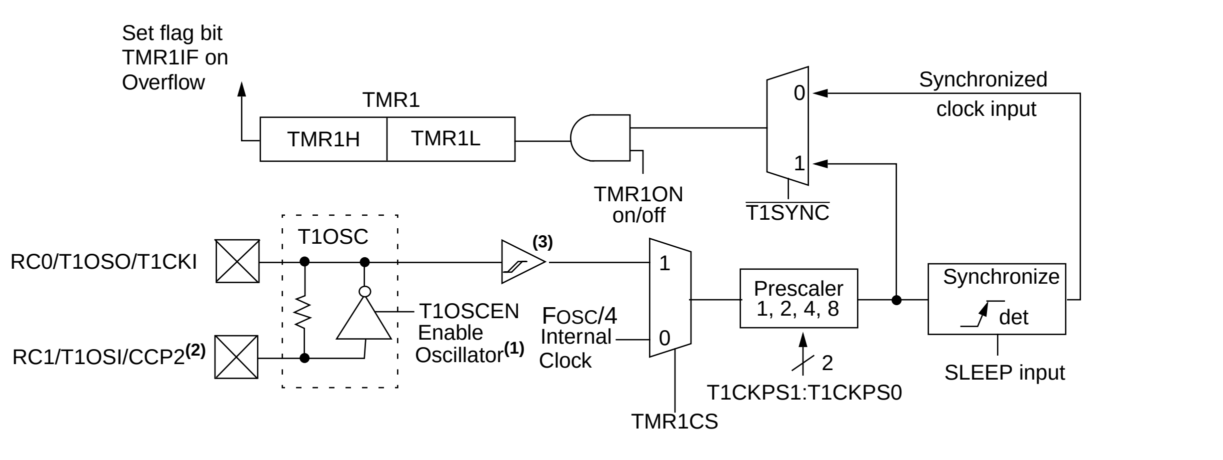
8.2.1 EXTERNAL CLOCK INPUT TIMING FOR SYNCHRONIZED COUNTER MODE

When an external clock input is used for Timer1 in synchronized counter mode, it must meet certain requirements. The external clock requirement is due to internal phase clock (Tosc) synchronization. Also, there is a delay in the actual incrementing of TMR1 after synchronization.

When the prescaler is 1:1, the external clock input is the same as the prescaler output. The synchronization of T1CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks. Therefore, it is necessary for T1CKI to be high for at least 2Tosc (and a small RC delay of 20 ns) and low for at least 2Tosc (and a small RC delay of 20 ns). Refer to the appropriate electrical specifications, parameters 45, 46, and 47.

When a prescaler other than 1:1 is used, the external clock input is divided by the asynchronous ripple-counter type prescaler so that the prescaler output is symmetrical. In order for the external clock to meet the sampling requirement, the ripple-counter must be taken into account. Therefore, it is necessary for T1CKI to have a period of at least 4Tosc (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T1CKI high and low time is that they do not violate the minimum pulse width requirements of 10 ns). Refer to the appropriate electrical specifications, parameters 40, 42, 45, 46, and 47.

FIGURE 8-2: TIMER1 BLOCK DIAGRAM



Note 1: When the T1OSCEN bit is cleared, the inverter and feedback resistor are turned off. This eliminates power drain.
2: The CCP2 module is not implemented in the PIC16C72.
3: For the PIC16C73 and PIC16C74, the Schmitt Trigger is not implemented in external clock mode.

11.4 I^{2}C™ Overview

This section provides an overview of the Inter-Integrated Circuit (I^{2}C) bus, with Section 11.5 discussing the operation of the SSP module in I^{2}C mode.

The I^{2}C bus is a two-wire serial interface developed by the Philips Corporation. The original specification, or standard mode, was for data transfers of up to 100 Kbps. The enhanced specification (fast mode) is also supported. This device will communicate with both standard and fast mode devices if attached to the same bus. The clock will determine the data rate.

The I^{2}C interface employs a comprehensive protocol to ensure reliable transmission and reception of data. When transmitting data, one device is the "master" which initiates transfer on the bus and generates the clock signals to permit that transfer, while the other device(s) acts as the "slave." All portions of the slave protocol are implemented in the SSP module's hardware, except general call support, while portions of the master protocol need to be addressed in the PIC16CXX software. Table 11-3 defines some of the I^{2}C bus terminology. For additional information on the I^{2}C interface specification, refer to the Philips document "*The I^{2}C bus and how to use it.*"#939839340011, which can be obtained from the Philips Corporation.

In the I^{2}C interface protocol each device has an address. When a master wishes to initiate a data transfer, it first transmits the address of the device that it wishes to "talk" to. All devices "listen" to see if this is their address. Within this address, a bit specifies if the master wishes to read-from/write-to the slave device. The master and slave are always in opposite modes (transmitter/receiver) of operation during a data transfer. That is they can be thought of as operating in either of these two relations:

- Master-transmitter and Slave-receiver
- Slave-transmitter and Master-receiver

In both cases the master generates the clock signal.

The output stages of the clock (SCL) and data (SDA) lines must have an open-drain or open-collector in order to perform the wired-AND function of the bus. External pull-up resistors are used to ensure a high level when no device is pulling the line down. The number of devices that may be attached to the I^{2}C bus is limited only by the maximum bus loading specification of 400 pF.

11.4.1 INITIATING AND TERMINATING DATA TRANSFER

During times of no data transfer (idle time), both the clock line (SCL) and the data line (SDA) are pulled high through the external pull-up resistors. The START and STOP conditions determine the start and stop of data transmission. The START condition is defined as a high to low transition of the SDA when the SCL is high. The STOP condition is defined as a low to high transition of the SDA when the SCL is high. Figure 11-14 shows the START and STOP conditions. The master generates these conditions for starting and terminating data transfer. Due to the definition of the START and STOP conditions, when data is being transmitted, the SDA line can only change state when the SCL line is low.

FIGURE 11-14: START AND STOP CONDITIONS

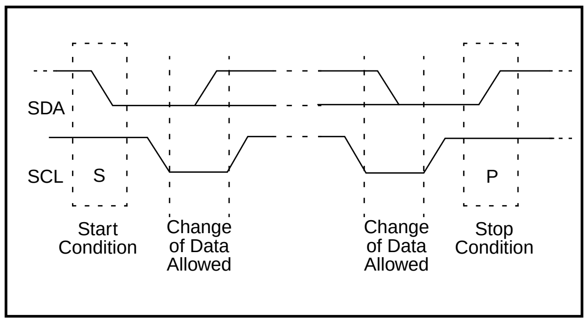


TABLE 11-3: I^{2}C BUS TERMINOLOGY

Term	Description
Transmitter	The device that sends the data to the bus.
Receiver	The device that receives the data from the bus.
Master	The device which initiates the transfer, generates the clock and terminates the transfer.
Slave	The device addressed by a master.
Multi-master	More than one master device in a system. These masters can attempt to control the bus at the same time without corrupting the message.
Arbitration	Procedure that ensures that only one of the master devices will control the bus. This ensure that the transfer data does not get corrupted.
Synchronization	Procedure where the clock signals of two or more devices are synchronized.

FIGURE 13-2: ADCON1 REGISTER (ADDRESS 9Fh)

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	PCFG2	PCFG1	PCFG0
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7-3: **Unimplemented:** Read as '0'

bit 2-0: **PCFG2:PCFG0**: A/D Port Configuration Control bits

PCFG2:PCFG0	RA0	RA1	RA2	RA5	RA3	RE0(1)	RE1(1)	RE2(1)	VREF
000	A	A	A	A	A	A	A	A	VDD
001	A	A	A	A	VREF	A	A	A	RA3
010	A	A	A	A	A	D	D	D	VDD
011	A	A	A	A	VREF	D	D	D	RA3
100	A	A	D	D	A	D	D	D	VDD
101	A	A	D	D	VREF	D	D	D	RA3
11x	D	D	D	D	D	D	D	D	—

A = Analog input

D = Digital I/O

Note 1: RE0, RE1, and RE2 are implemented on the PIC16C74/74A/77 only.

14.2 Oscillator Configurations

Applicable Devices						
72	73	73A	74	74A	76	77

14.2.1 OSCILLATOR TYPES

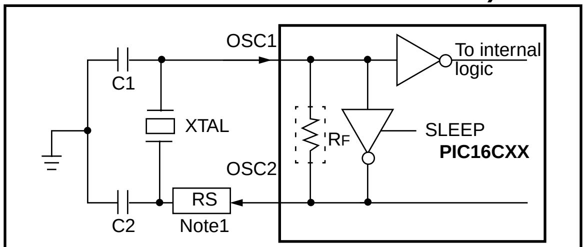
The PIC16CXX can be operated in four different oscillator modes. The user can program two configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low Power Crystal
- XT Crystal/Resonator
- HS High Speed Crystal/Resonator
- RC Resistor/Capacitor

14.2.2 CRYSTAL OSCILLATOR/CERAMIC RESONATORS

In XT, LP or HS modes a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 14-3). The PIC16CXX Oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1/CLKIN pin (Figure 14-4).

FIGURE 14-3: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)



See Table 14-1 and Table 14-2 for recommended values of C1 and C2.

Note 1: A series resistor may be required for AT strip cut crystals.

FIGURE 14-4: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

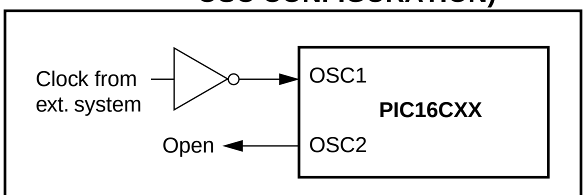


TABLE 14-1: CERAMIC RESONATORS

Mode	Freq	OSC1	OSC2
Ranges Tested:			
XT	455 kHz 2.0 MHz 4.0 MHz	68 - 100 pF 15 - 68 pF 15 - 68 pF	68 - 100 pF 15 - 68 pF 15 - 68 pF
HS	8.0 MHz 16.0 MHz	10 - 68 pF 10 - 22 pF	10 - 68 pF 10 - 22 pF
These values are for design guidance only. See notes at bottom of page.			
Resonators Used:			
455 kHz	Panasonic EFO-A455K04B	± 0.3%	
2.0 MHz	Murata Erie CSA2.00MG	± 0.5%	
4.0 MHz	Murata Erie CSA4.00MG	± 0.5%	
8.0 MHz	Murata Erie CSA8.00MT	± 0.5%	
16.0 MHz	Murata Erie CSA16.00MX	± 0.5%	
All resonators used did not have built-in capacitors.			

TABLE 14-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Osc Type	Crystal Freq	Cap. Range C1	Cap. Range C2
LP	32 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15-33 pF	15-33 pF
	20 MHz	15-33 pF	15-33 pF
These values are for design guidance only. See notes at bottom of page.			
Crystals Used			
32 kHz	Epson C-001R32.768K-A	± 20 PPM	
200 kHz	STD XTL 200.000KHz	± 20 PPM	
1 MHz	ECS ECS-10-13-1	± 50 PPM	
4 MHz	ECS ECS-40-20-1	± 50 PPM	
8 MHz	EPSON CA-301 8.000M-C	± 30 PPM	
20 MHz	EPSON CA-301 20.000M-C	± 30 PPM	

Note 1: Recommended values of C1 and C2 are identical to the ranges tested (Table 14-1).
2: Higher capacitance increases the stability of oscillator but also increases the start-up time.
3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.
4: Rs may be required in HS mode as well as XT mode to avoid overdriving crystals with low drive level specification.

FIGURE 14-10: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD}): CASE 1

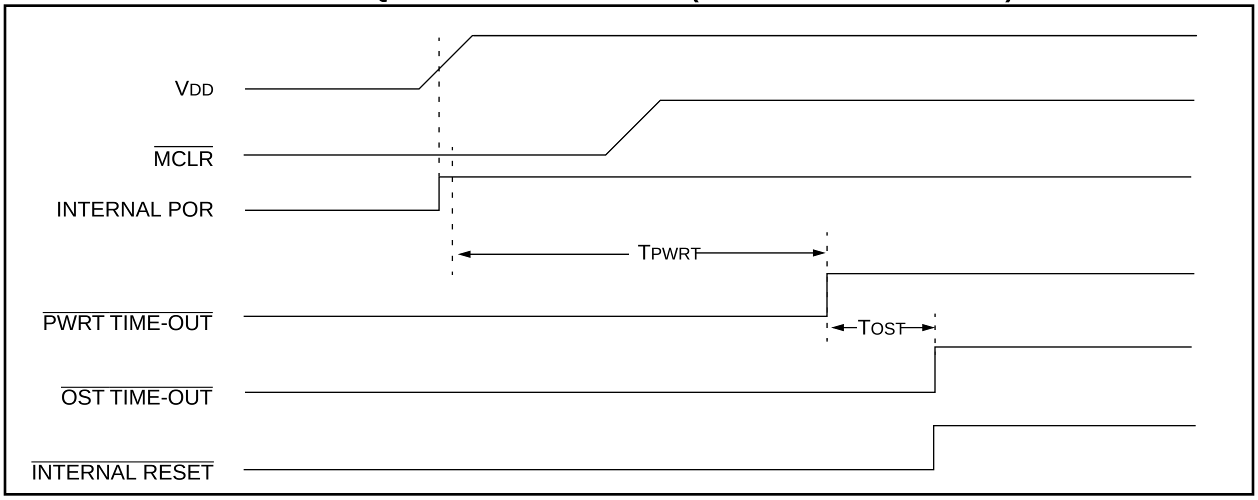


FIGURE 14-11: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD}): CASE 2

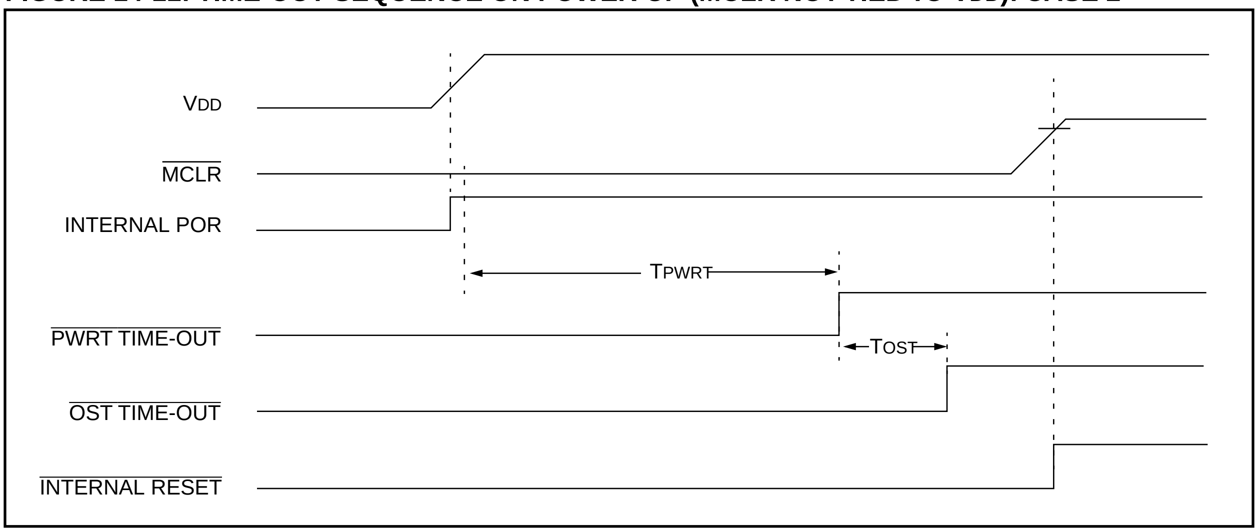
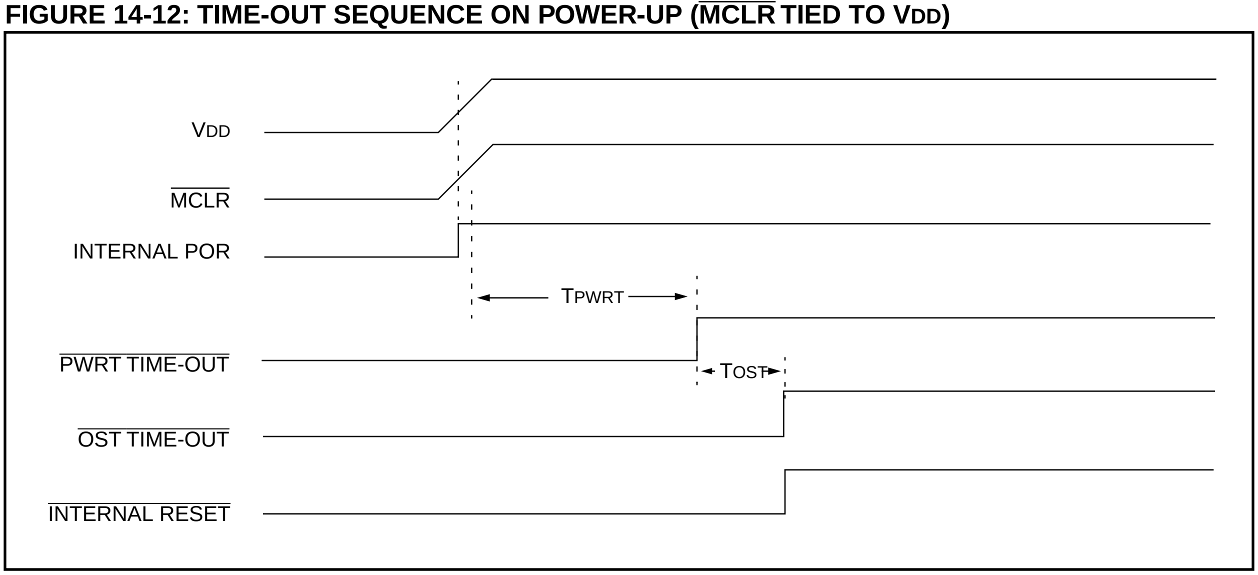


FIGURE 14-12: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ TIED TO V_{DD})



14.5 Interrupts

Applicable Devices						
72	73	73A	74	74A	76	77

The PIC16C7X family has up to 12 sources of interrupt. The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

> **Note:** Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

A global interrupt enable bit, GIE (INTCON<7>) enables (if set) all un-masked interrupts or disables (if cleared) all interrupts. When bit GIE is enabled, and an interrupt's flag bit and mask bit are set, the interrupt will vector immediately. Individual interrupts can be disabled through their corresponding enable bits in various registers. Individual interrupt bits are set regardless of the status of the GIE bit. The GIE bit is cleared on reset.

The "return from interrupt" instruction, `RETFIE`, exits the interrupt routine as well as sets the GIE bit, which re-enables interrupts.

The RB0/INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flags are contained in the special function registers PIR1 and PIR2. The corresponding interrupt enable bits are contained in special function registers PIE1 and PIE2, and the peripheral interrupt enable bit is contained in special function register INTCON.

When an interrupt is responded to, the GIE bit is cleared to disable any further interrupt, the return address is pushed onto the stack and the PC is loaded with 0004h. Once in the interrupt service routine the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs (Figure 14-17). The latency is the same for one or two cycle instructions. Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

> **Note:** For the PIC16C73/74, if an interrupt occurs while the Global Interrupt Enable (GIE) bit is being cleared, the GIE bit may unintentionally be re-enabled by the user's Interrupt Service Routine (the `RETFIE` instruction). The events that would cause this to occur are:
>
> 1. An instruction clears the GIE bit while an interrupt is acknowledged.
> 2. The program branches to the Interrupt vector and executes the Interrupt Service Routine.
> 3. The Interrupt Service Routine completes with the execution of the `RETFIE` instruction. This causes the GIE bit to be set (enables interrupts), and the program returns to the instruction after the one which was meant to disable interrupts.
>
> Perform the following to ensure that interrupts are globally disabled:

```
LOOP BCF   INTCON, GIE  ; Disable global
                        ;  interrupt bit
     BTFSC INTCON, GIE  ; Global interrupt
                        ;   disabled?
     GOTO  LOOP         ; NO, try again
        :               ;   Yes, continue
                        ;   with program
                        ;   flow
```

15.1 Instruction Descriptions

ADDLW **Add Literal and W**

Syntax: [*label*] ADDLW k

Operands: $0 \le k \le 255$

Operation: (W) + k → (W)

Status Affected: C, DC, Z

Encoding:

`11`	`111x`	`kkkk`	`kkkk`

Description: The contents of the W register are added to the eight bit literal 'k' and the result is placed in the W register.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process data	Write to W

Example: `ADDLW 0x15`

Before Instruction
W = 0x10
After Instruction
W = 0x25

ANDLW **AND Literal with W**

Syntax: [*label*] ANDLW k

Operands: $0 \le k \le 255$

Operation: (W) .AND. (k) → (W)

Status Affected: Z

Encoding:

`11`	`1001`	`kkkk`	`kkkk`

Description: The contents of W register are AND’ed with the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal "k"	Process data	Write to W

Example `ANDLW 0x5F`

Before Instruction
W = 0xA3
After Instruction
W = 0x03

ADDWF **Add W and f**

Syntax: [*label*] ADDWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (W) + (f) → (destination)

Status Affected: C, DC, Z

Encoding:

`00`	`0111`	`dfff`	`ffff`

Description: Add the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write to destination

Example `ADDWF FSR, 0`

Before Instruction
W = 0x17
FSR = 0xC2
After Instruction
W = 0xD9
FSR = 0xC2

ANDWF **AND W with f**

Syntax: [*label*] ANDWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (W) .AND. (f) → (destination)

Status Affected: Z

Encoding:

`00`	`0101`	`dfff`	`ffff`

Description: AND the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write to destination

Example `ANDWF FSR, 1`

Before Instruction
W = 0x17
FSR = 0xC2
After Instruction
W = 0x17
FSR = 0x02

TABLE 16-1: DEVELOPMENT TOOLS FROM MICROCHIP

		PIC12C5XX	PIC14000	PIC16C5X	PIC16CXXX	PIC16C6X	PIC16C7XX	PIC16C8X	PIC16C9XX	PIC17C4X	PIC17C75X	24CXX 25CXX 93CXX	HCS200 HCS300 HCS301
Emulator Products	PICMASTER®/ PICMASTER-CE In-Circuit Emulator	✓	✓	✓	✓	✓	✓	✓	✓	✓	Available 3Q97		
	ICEPIC Low-Cost In-Circuit Emulator	✓		✓	✓	✓	✓	✓					
Software Tools	MPLAB™ Integrated Development Environment	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
	MPLAB™ C Compiler	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
	*fuzzy*TECH®-MP Explorer/Edition Fuzzy Logic Dev. Tool	✓	✓	✓	✓	✓	✓	✓	✓	✓			
	MP-DriveWay™ Applications Code Generator			✓	✓	✓	✓	✓		✓			
	Total Endurance™ Software Model											✓	
Programmers	PICSTART® Lite Ultra Low-Cost Dev. Kit			✓		✓	✓	✓					
	PICSTART® Plus Low-Cost Universal Dev. Kit	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
	PRO MATE® II Universal Programmer	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
	KEELOQ® Programmer												✓
Demo Boards	SEEVAL® Designers Kit											✓	
	PICDEM-1			✓	✓			✓		✓			
	PICDEM-2					✓	✓						
	PICDEM-3								✓				
	KEELOQ® Evaluation Kit												✓

Applicable Devices	72	73	73A	74	74A	76	77

19.3 DC Characteristics: PIC16C73A/74A-04 (Commercial, Industrial, Extended) PIC16C73A/74A-10 (Commercial, Industrial, Extended) PIC16C73A/74A-20 (Commercial, Industrial, Extended) PIC16LC73A/74A-04 (Commercial, Industrial)

DC CHARACTERISTICS	Standard Operating Conditions (unless otherwise stated) Operating temperature -40˚C ≤ TA ≤ +125˚C for extended, -40˚C ≤ TA ≤ +85˚C for industrial and 0˚C ≤ TA ≤ +70˚C for commercial Operating voltage VDD range as described in DC spec Section 19.1 and Section 19.2.						
Param No.	Characteristic	Sym	Min	Typ †	Max	Units	Conditions
	Input Low Voltage						
	I/O ports	VIL					
D030	with TTL buffer		VSS	-	0.15VDD	V	For entire VDD range
D030A			VSS	-	0.8V		4.5V ≤ VDD ≤ 5.5V
D031	with Schmitt Trigger buffer		VSS	-	0.2VDD	V	
D032	$\overline{MCLR}$, OSC1 (in RC mode)		VSS	-	0.2VDD	V	
D033	OSC1 (in XT, HS and LP)		VSS	-	0.3VDD	V	Note1
	Input High Voltage						
	I/O ports	VIH		-			
D040	with TTL buffer		2.0	-	VDD	V	4.5V ≤ VDD ≤ 5.5V
D040A			0.25VDD + 0.8V	-	VDD	V	For entire VDD range
D041	with Schmitt Trigger buffer		0.8VDD	-	VDD	V	For entire VDD range
D042	$\overline{MCLR}$		0.8VDD	-	VDD	V	
D042A	OSC1 (XT, HS and LP)		0.7VDD	-	VDD	V	Note1
D043	OSC1 (in RC mode)		0.9VDD	-	VDD	V	
D070	PORTB weak pull-up current	IPURB	50	250	400	μA	VDD = 5V, VPIN = VSS
	Input Leakage Current (Notes 2, 3)						
D060	I/O ports	IIL	-	-	±1	μA	Vss ≤ VPIN ≤ VDD, Pin at hi-impedance
D061	$\overline{MCLR}$, RA4/T0CKI		-	-	±5	μA	Vss ≤ VPIN ≤ VDD
D063	OSC1		-	-	±5	μA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
	Output Low Voltage						
D080	I/O ports	VOL	-	-	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C
D080A			-	-	0.6	V	IOL = 7.0 mA, VDD = 4.5V, -40°C to +125°C
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C
D083A			-	-	0.6	V	IOL = 1.2 mA, VDD = 4.5V, -40°C to +125°C

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C7X be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

Applicable Devices	72	73	73A	74	74A	76	77

20.0 ELECTRICAL CHARACTERISTICS FOR PIC16C76/77

Absolute Maximum Ratings †

Ambient temperature under bias..-55 to +125˚C

Storage temperature .... -65˚C to +150˚C

Voltage on any pin with respect to VSS (except VDD, $\overline{\text{MCLR}}$. and RA4)..-0.3V to (VDD + 0.3V)

Voltage on VDD with respect to VSS .... -0.3 to +7.5V

Voltage on $\overline{\text{MCLR}}$ with respect to VSS (Note 2) .... 0 to +14V

Voltage on RA4 with respect to Vss .... 0 to +14V

Total power dissipation (Note 1)...1.0W

Maximum current out of VSS pin ....300 mA

Maximum current into VDD pin ....250 mA

Input clamp current, IIK (VI < 0 or VI > VDD) ....±20 mA

Output clamp current, IOK (VO < 0 or VO > VDD)..±20 mA

Maximum output current sunk by any I/O pin...25 mA

Maximum output current sourced by any I/O pin ....25 mA

Maximum current sunk by PORTA, PORTB, and PORTE (combined) (Note 3)...200 mA

Maximum current sourced by PORTA, PORTB, and PORTE (combined) (Note 3) ....200 mA

Maximum current sunk by PORTC and PORTD (combined) (Note 3)..200 mA

Maximum current sourced by PORTC and PORTD (combined) (Note 3)...200 mA

Note 1: Power dissipation is calculated as follows: Pdis = VDD x {IDD - ∑ IOH} + ∑ {(VDD - VOH) x IOH} + ∑(VOl x IOL)

Note 2: Voltage spikes below VSS at the $\overline{\text{MCLR}}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a “low” level to the $\overline{\text{MCLR}}$ pin rather than pulling this pin directly to VSS.

Note 3: PORTD and PORTE are not implemented on the PIC16C76.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Applicable Devices	72	73	73A	74	74A	76	77

TABLE 20-8: SPI MODE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
70*	TssL2scH, TssL2scL	$\overline{SS}$↓ to SCK↓ or SCK↑ input	TCY	—	—	ns	
71*	TscH	SCK input high time (slave mode)	TCY + 20	—	—	ns	
72*	TscL	SCK input low time (slave mode)	TCY + 20	—	—	ns	
73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	100	—	—	ns	
74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	100	—	—	ns	
75*	TdoR	SDO data output rise time	—	10	25	ns	
76*	TdoF	SDO data output fall time	—	10	25	ns	
77*	TssH2doZ	$\overline{SS}$↑ to SDO output hi-impedance	10	—	50	ns	
78*	TscR	SCK output rise time (master mode)	—	10	25	ns	
79*	TscF	SCK output fall time (master mode)	—	10	25	ns	
80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	—	—	50	ns	
81*	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge	TCY	—	—	ns	
82*	TssL2doV	SDO data output valid after $\overline{SS}$↓ edge	—	—	50	ns	
83*	TscH2ssH, TscL2ssH	$\overline{SS}$ ↑ after SCK edge	1.5TCY + 40	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices	72	73	73A	74	74A	76	77

FIGURE 21-22: TYPICAL XTAL STARTUP TIME vs. VDD (LP MODE, 25°C)

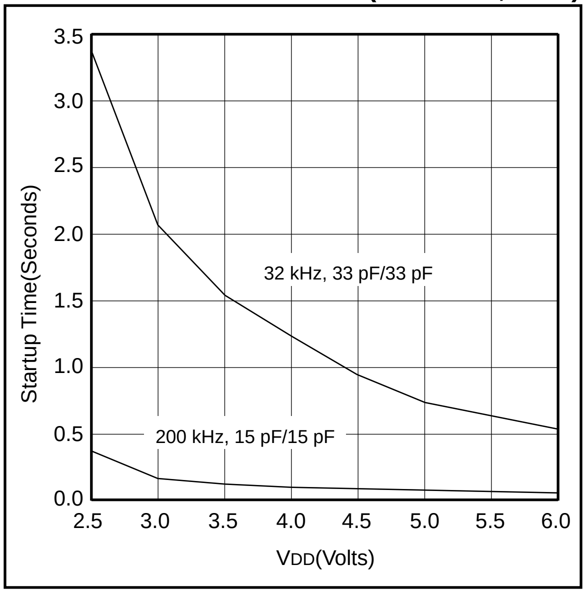


FIGURE 21-23: TYPICAL XTAL STARTUP TIME vs. VDD (HS MODE, 25°C)

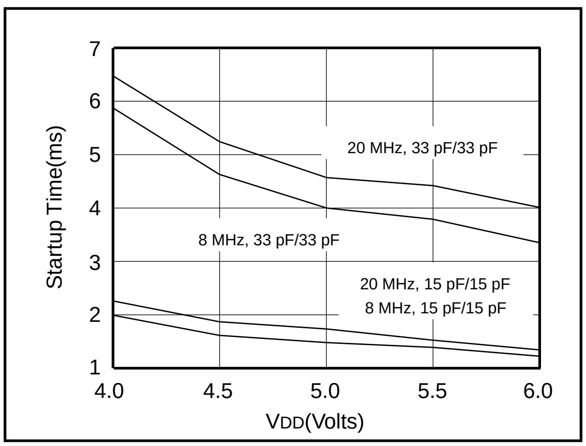


FIGURE 21-24: TYPICAL XTAL STARTUP TIME vs. VDD (XT MODE, 25°C)

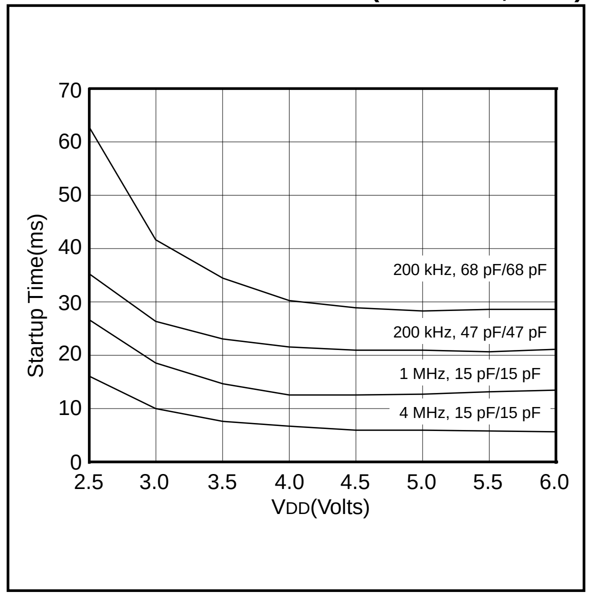


TABLE 21-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATORS

Osc Type	Crystal Freq	Cap. Range C1	Cap. Range C2
LP	32 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15-33 pF	15-33 pF
	20 MHz	15-33 pF	15-33 pF

Crystals Used		
32 kHz	Epson C-001R32.768K-A	± 20 PPM
200 kHz	STD XTL 200.000KHz	± 20 PPM
1 MHz	ECS ECS-10-13-1	± 50 PPM
4 MHz	ECS ECS-40-20-1	± 50 PPM
8 MHz	EPSON CA-301 8.000M-C	± 30 PPM
20 MHz	EPSON CA-301 20.000M-C	± 30 PPM

Data based on matrix samples. See first page of this section for details.